

**IN THE CLAIMS:**

None of the claims have been amended herein. All of the pending claims 1 through 13 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as previously amended.

**Listing of Claims:**

1. (Previously presented) A clamping method for attaching a portion of a wire to a portion of at least one lead finger of a lead frame using a clamp in a wire bonding apparatus having a heat block for supporting the at least one lead finger during a wire bonding operation comprising:  
providing an independently movable clamp for movement in at least one x-axis direction, at least one y-axis direction, and at least one z-axis direction; and  
positioning the independently movable clamp over a portion of the at least one lead finger for clamping the at least one lead finger in position on a portion of the heat block for attaching of at least the portion of the wire thereto during a wire bond operation of the wire bonding apparatus.
2. (Previously presented) The clamping method of claim 1, further comprising:  
actuating the wire bonding apparatus for attaching the portion of the wire to the at least one lead finger.
3. (Previously presented) The clamping method of claim 2, further comprising:  
disengaging the independently movable clamp from the portion of the at least one lead finger before removal of the wire bonding apparatus from the at least one lead finger on the heat block.

4. (Previously presented) The clamping method of claim 1, wherein the independently movable clamp comprises a resiliently mounted clamp.

5. (Previously presented) A method for attaching a portion of a wire to a portion of a lead finger of a lead frame using a first clamp and an independently movable clamp in a wire bonding apparatus having a heat block comprising:

positioning the first clamp over the portion of the lead finger for clamping the lead finger in a position on the heat block during attaching the portion of the wire thereto, the first clamp comprising a clamp movable in at least one x-axis direction, at least one y-axis direction, and at least one z-axis direction; and  
positioning the independently movable clamp over another portion of the lead finger for retaining the lead finger in the position on the portion of the heat block during attaching of the wire thereto.

6. (Previously presented) The method of claim 5, further comprising:  
actuating apparatus for attaching the portion of the wire to the portion of the lead finger in the wire bonding apparatus.

7. (Previously presented) The method of claim 6, further comprising:  
removing the independently movable clamp from engagement with the portion of the lead finger before removal of the wire bonding apparatus from the lead finger.

8. (Previously presented) The method of claim 5, wherein the independently movable clamp comprises a resiliently mounted clamp.

9. (Previously presented) A method for attaching at least a portion of a wire to a portion of a lead finger of a lead frame using a plurality of clamps in a wire bonding apparatus having a heat block comprising:  
positioning a first independent clamp over the portion of the lead finger for retaining the lead finger on a portion of the heat block for bonding a portion of the wire thereto, the first independent clamp movable in at least one x-axis direction, at least one y-axis direction, and at least one z-axis direction; and  
positioning a second independent clamp over another portion of the lead finger for restraining the lead finger in a position on a portion of the heat block for bonding of the wire thereto, the second independent clamp movable in the at least one x-axis direction, the at least one y-axis direction, and the at least one z-axis direction.
10. (Previously presented) The method of claim 9, further comprising:  
actuating an apparatus for bonding the portion of the wire to the portion of the lead finger.
11. (Previously presented) The method of claim 10, further comprising:  
removing the second independent clamp from the another portion of the lead finger before removal of the apparatus from the lead finger.
12. (Previously presented) The method of claim 9, wherein the second independent clamp comprises a clamp for positioning between the first independent clamp and an end of the lead finger.
13. (Previously presented) The method of claim 9, wherein the first independent clamp and the second independent clamp each comprise a clamp that is independently movable with respect to each other and the lead finger.